ABSTRACT

INTEGRATED CIRCUIT PACKAGE SYSTEM WITH ARRAY OF EXTERNAL INTERCONNECTS

An integrated circuit package system includes: forming an array of external interconnects with an intersecting region between the external interconnects; removing the intersecting region for forming an isolation hole between the external interconnects; mounting an integrated circuit die over the external interconnects; connecting an internal interconnect between the integrated circuit die and the external interconnects; and forming a package encapsulation over the integrated circuit die with the external interconnects partially exposed. (Fig. 1)